

CATALOG OF MOLYBDENUM PRODUCTS

Molybdenum Products

Date of Preparation: 08/18/2011

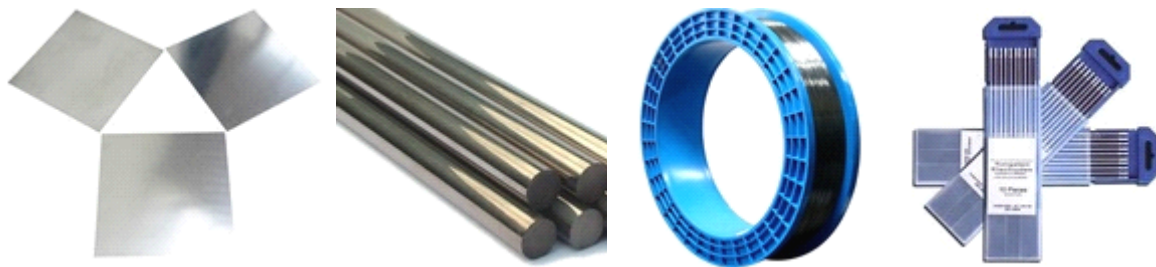
Reason for Issue: Updated Format

Chemical Name: Tungsten Carbide

Chemical Family: Refractory Metal (non-ferrous metal)

Chemical Formula: WC

E-Biz Center of China Tungsten Industry Association



MORE INFORMATION

Web: www.tungstenalloys.net

Email: ebiz@ctia.com.cn

PRODUCTS CONTENTS

1. MOLYBDENUM MATERIAL.....	2
2. MOLYBDENUM PLATES / SHEET / FOIL.....	3
3. MOLYBDENUM ROUND ROD / BAR.....	4
4. MOLYBDENUM WIRE.....	5
5. MOLYBDENUM TARGETS / SPUTTERING TARGETS.....	6
6. MOLYBDENUM CRUCIBLE.....	6
7. MOLYBDENUM PARTS.....	7
COMPANY INFORMATION.....	8

1. MOLYBDENUM MATERIAL

Symbol:	Mo
Atomic Number:	42
Atomic Weight:	95.94
Density:	10.22 gm/cc
Melting Point:	2617 °C (2890.15 K, 4742.6 °F)
Boiling Point:	4612.0 °C (4885.15 K, 8333.6 °F)
Thermal Conductivity:	138 W/m K at 20°C
Coefficient of Thermal Expansion:	4.8 x 10 ⁻⁶ / K at 25 °C

Grade of molybdenum material

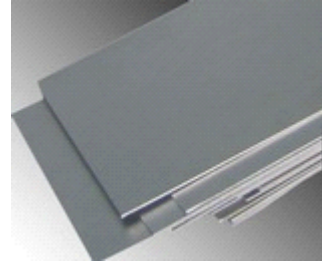
Grade	Mo-1	Mo-2	Mo-3
Mo (%) ≥	99.95	99.95	99.92
Pb			0.001
Bi			0.001
Sn			0.001
Sd			0.001
Cd			0.001
Fe	0.005	0.006	0.030
Ni	0.002	0.001	0.005
Other Element Cont (%) ≤			
Al	0.002	0.002	0.005
Si	0.003	0.001	0.010
Ca	0.002	0.002	0.004
Mg	0.001	0.001	0.003
P	0.001	0.001	0.002
C	0.005	0.003	0.010
O	0.003	0.005	0.008
N	0.001	0.001	
Use for example	Drawing Molybdenum wire	Spraying Molybdenum wires	High Temperature Components

2. MOLYBDENUM PLATES / SHEET / FOIL

Production process

Materials → hot rolling → annealing → cold rolling → leveling → annealing → machining → Molybdenum plates

Material from .005 inches to .090 inches in thickness is classified as molybdenum sheet. It is used for fabrication of sintering boats, high temperature furnace heating elements and heat shields. Standard availability is described below. Other sizes and tolerances are available.



The specification of molybdenum sheet

Thickness	Max. Width
.005" to .015"	24"
> .015" to .040"	24"
> .040" to .090"	24"
Length is dependant on surface condition required and width.	

Molybdenum sheet standard thickness tolerance

Thickness	.25" to 6"	6" to 12"	12" to 24"
.005" - .009"	± .0005"	± .0005"	± .002"
.009" - .015"	± .0008"	± .0009"	± 10%
.015" - .020"	± .0010"	± .0010"	± 10%
.020" - .040"	± .0015"	± .0015"	± 10%
.040" - .050"	± .003"	± .003"	± 10%
.050" - .065"	± .004"	± .004"	± .004"
.065" - .090"	± .005"	± .005"	± .005"

Molybdenum sheet standard width tolerance

Thickness	.25" to 6"	6" to 12"	12" to 24"
.005" - .009"	± .012"	± .015"	± .025"
.009" - .015"	± .012"	± .015"	± .025"
.015" - .020"	± .012"	± .020"	± .025"
.020" - .040"	± .020"	± .030"	± .030"
.040" - .050"	± .020"	± .030"	± .030"
.050" - .065"	± .020"	± .030"	± .030"
.065" - .090"	± .030"	± .031"	± .031"

3. MOLYBDENUM ROUND ROD / BAR



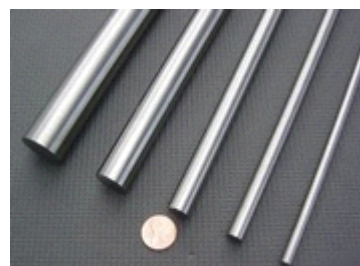
Molybdenum round rod / bar

1. Diameter: 1.0-100.0mm
2. Length: 50-2000mm
3. Density: 10.15g/cm³
4. Surface: Sintering surface, Forged surface, Ground surface

Production process

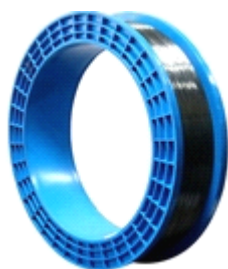
Materials → CIP → IF induction sintering → forging → annealing → mechanical processing → Molybdenum rod

Molybdenum rod divided forging molybdenum rod and polished molybdenum rod; forging molybdenum rod surface is allowed to have oxidize film and slight forging hammer mark; polished molybdenum rod surface presents metallic luster and has no oxidized phenomenon notably; the two surfaces have no defects, such as divided layer, crackle, burr and vertical crackle, etc.



We produce pure and lanthanide doped molybdenum rod. The lanthanide doped molybdenum rods are targeted for use in higher temperature applications where ductility is retained after recrystallization for material with smaller cross sections.

4. MOLYBDENUM WIRE



Molybdenum wire / heater

1. Grade: Mo-1, Mo-2, Mo-3
2. Density: not less than 10.17g/cm³
3. Appearance: black surface

Specifications of molybdenum wire

mm	diameter	length	Diameter tolerance	surface	State
rod	8.0~16.0	10~850	10~660	Black	forged
	3.0~8.0	10~5000	10~800	Black	forged
wire	1.5~3.0	10~8000	10~1600	Black	drawing
	0.5~1.5	10~8000	10~2650	Black	drawing

Molybdenum wire recommends applications

Grade	Description	Recommend Application
MO1	Pure molybdenum wires	Used in making heat parts for electronic vacuum device, heating parts, hooks of various type of bulb, mandrels of tungsten coiled coil wire, etc. Used for wire cutting
MO2	Pure molybdenum rods	Used in making electronic vacuum devices, electrode for the gas discharge tube and lamp, support and lead for electron tubes.
MO3	Molybdenum mixed with other elements	High - temperature structure material (printer needle, nut, screw) halogen lamp support, heating filaments, the axis in radial tube.

5. MOLYBDENUM TARGETS / SPUTTERING TARGETS



Molybdenum targets / Sputtering Targets

1. Appearance: Silver white metal luster
2. Purity: $\text{Mo} \geq 99.92\%$
3. Density: not less than 10.17g/cm^3
4. Supply state: Surface polishing, CNC machine processing

Production process

Materials → CIP → IF induction sintering → hot rolling → annealing → cold rolling → annealing → cutting → machining → molybdenum targets

Application of molybdenum targets

Molybdenum target is mainly used in plasma sputtering industry. With the electric field, electron collided with the argon atom when fly to the substrate, and then argon atoms and electrics were ionized .the electrics fly to the substrate while argon atoms accelerate to bomb the target, the neutral atoms (or molecules) in the target deposit on the substrate and become the coating.

Since the molybdenum resistant to high temperature and corrosion, molybdenum targets are widely used in petroleum chemical industry, aviation, machine manufacturing, and electronics semiconductor industries and so on.

6. MOLYBDENUM CRUCIBLE



Molybdenum crucible

1. Purity: $W \geq 99.95\%$
2. Appearance: silver grey metal luster
3. Supply state: sintering or processing
4. Quality standard: according to customer

Production process

Raw materials (MOLYBDENUM powder) → isostatic pressing → mechanical processing → IF induction sintering → mechanical processing → detection checks → MOLYBDENUM crucibles

Application of molybdenum crucible

Since the melting point of molybdenum has reached 2617°C , molybdenum crucible is widely applied in industry furnace such as sapphire growth furnace, quartz glass melting furnace, and rare earth smelting furnace. the temperature in working environment of molybdenum crucible is above 2000°C . for sapphire crystal growth furnace, high-purity, high-density, no internal-crack molybdenum crucible with other features of exact measurement and smooth surface has decisive influence on success ratio of seed growth, quality control of pulling crystal, metamictization pot-committed and service life during sapphire growth process, and we are willing to be checked by professional units.

Specifications of molybdenum crucible

diameter(mm)	thickness(mm)	Height(mm)	Surface finish	inner surface finish	Inner bottom finish
30 ~ 50	2 ~ 10	≤500	≤Ra2.0	≤Ra2.4	≤Ra2.8
50 ~ 100	3 ~ 15	≤1000	≤Ra2.0	≤Ra2.4	≤Ra2.8
100 ~ 150	3 ~ 15	≤1000	≤Ra2.0	≤Ra2.4	≤Ra2.8
150 ~ 200	5 ~ 20	≤1000	≤Ra2.0	≤Ra2.4	≤Ra2.8
200 ~ 300	8 ~ 20	≤1000	≤Ra2.0	≤Ra2.4	≤Ra2.8
300 ~ 400	8 ~ 30	≤1000	≤Ra2.0	≤Ra2.4	≤Ra2.8
400 ~ 450	8 ~ 30	≤1000	≤Ra2.0	≤Ra2.4	≤Ra2.8
450 ~ 600	8 ~ 30	≤1000	≤Ra2.0	≤Ra2.4	≤Ra2.8

MORE INFORMATION

Web: www.tungstenalloys.net

Email: ebiz@ctia.com.cn

7. MOLYBDENUM PARTS

Molybdenum fabricated parts



Most of our molybdenum fabricated parts and molybdenum fabricated parts are used as ion implantation parts for semiconductor industry and as sputtering targets for the solar industry. We also produce parts for x-ray and electron tubes which be made of molybdenum and molybdenum. Molybdenum crucibles and molybdenum

crucibles for quartz melting and high temperature vacuum furnace are also our main products.

Furnace components

High temperature industrial furnaces frequently require molybdenum components for their successful operation. Molybdenum rod or flat sheet heating elements are used in vacuum and hydrogen furnaces. Molybdenum metal is also used for heat shielding and other furnace components and structures.



Electronic/Semiconductor equipment components

Silicon wafer processing relies on the use of ion implantation systems which inject ions at high energy directly into silicon wafer surfaces. The ion plasma source is energized via molybdenum electrodes which operates within fabricated molybdenum or molybdenum arc chambers.